

IBIS-ISS Package Modeling Discussion

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Agenda

- Posted 8/12/7 Presentation
 - <http://tinyurl.com/cvykehz>
- Comments During Presentation and Received by E-mail
- Response to Comments Received by E-mail
- Open Discussion on Additional Questions on Presentation
- Open Discussion on Following Questions
 - Does the functionality described in this presentation satisfy your needs to generate package and on-die models using that your customers require?
 - If not, what additional functionality do you need?
- Next Steps

Comments During Presentation and Received by E-mail

- Are Supply Voltages Values Necessary?
- Are X-Y Coordinates Necessary for Pins and Die Pads?
- Need to add association of Power Clamp and Ground Clamp supply signal names to [Models]
- A Related Set of Comments
 - “Ports” “Sparse Ports”
 - Functionality was agreed to but alternative method to define the ports of subckts requested.
 - FEXT/NEXT was confusing
 - Both Victim/Interface Modeling Should have Same Mechanism to Indicate Victim/Aggressor Channels

Why Supply Voltages Values Necessary

- The [Model] [Voltage Range] describes the test conditions that were used to generate the Ramp, IV and VT data in a [Model]
 - Consider a coupled simulation that has two [Model]s, and the two [Model] Ramp, IV and VT data where generated with different [Voltage Range] test conditions.
 - What Voltage should be applied to the Pin of the package?
 - How does the IC Vendor tell the EDA tool the typ/min/max Voltage applied at the package pin?
- I believe the only answer to the above two questions is adding records to IBIS to indicate the typ/min/max Supply Voltages applied at the package pin

Are X-Y Coordinates Necessary for Pins and Die Pads?

- No, but they can be useful
- Board, Package and On-Die Models are generated from three different tools. What “Handles” does each tool have to identify a Port of the model.
 - PCB Layout
 - Reference Designator / Pin Number (Pin_name)
 - PCB Cad Net Name
 - X-Y Board Coordinate
 - Package Layout
 - Pins
 - Board Connector Designator / Pin Number (Pin_name)
 - Package Cad Net Name
 - X-Y Package Coordinate
 - Die Pads
 - Die Connector Designator / Pin Number (Pin_name)
 - Package Cad Net Name
 - X-Y Package Coordinate
 - IC Layout
 - Die Pads
 - Chip Connector Designator / Pin Number (Pin_name)
 - Chip Cad Net Name
 - X-Y Chip Coordinate

X-Y Coordinates are the Most Reliable Method of Making Connection Between Board/Package/Chip Models

- How to make connections between Package and Board?
 - Pin Number?
 - Sometimes reliable, sometime not
 - CAD Net Name?
 - Unreliable, Fuzzy Logic an be useful
 - X-Y Coordinate
 - Reliable
 - Can create examples that break this method
 - Practically, such examples are very rare, if not existent, and can be further resolved using Fuzzy Logic on Pin Number and Net Name
- How to make connections between Package and Chip?
 - Pin Number?
 - Rarely reliable
 - CAD Net Name?
 - Rarely reliable
 - X-Y Coordinate
 - Reliable
 - Can create examples that break this method
 - Practically, such examples are very rare, if not existent, and can be further resolved using Fuzzy Logic on Pin Number and Net Name
- Note that x-y coordinates are used as an aid to generating Package and On-Die models, and are not used in the IBIS-ISS Package or On-Die Models

Adding association of Power Clamp and Ground Clamp supply signal names to [Models]

[Model] DQ

Pullup_Signal_name

VDD

Pulldown_Signal_name

VSS

Power_clamp_Signal_name

VDD_Clamp

Ground_clamp_Signal_name

VSS_Clamp

Ports Interface Needs Improvement!

- The following example address the comments made during the 8/7/12 presentations and e-mails received.
- Thanks for the suggestions made.

Rambus Forked Clock

```
(Package_models
  (Xclk
    (File      xclk.mod)
    (subckt    xclk)
  | (Ports    A1 A2 A3 A4 D.A1 D.A2)
    (Model_ports
      (1 (Type Pin) (Pin_name A1))
      (2 (Type Pin) (Pin_name A2))
      (3 (Type Pin) (Pin_name A3))
      (4 (Type Pin) (Pin_name A4))
      (5 (Type Pad) (Pad_name D.A1))
      (6 (Type Pad) (Pad_name D.A2))
    )
  )
)
```

By Model_name

(Package_models

(DQ

(File pkg1.mod)

(Subckt (Corner pkg1_typ pkg1_min pkg1_max))

(Length (Range 15 11 21))

(Parameters Length)

(Model_ports Pin Pad

(1 (Type Pin) (Model_name DQ))

(2 (Type Pad) (Model_name DQ))))

(DQS

(File pkg2.mod)

(Subckt (Corner pkg2_typ pkg2_min pkg2_max))

(Length (Range 15 11 21))

(Parameters Length)

(1 (Type Pin) (Polarity +) (Model_name DQS))

(2 (Type Pin) (Polarity -) (Model_name DQS))

(1 (Type Pad) (Polarity +) (Model_name DQS))

(2 (Type Pad) (Polarity -) (Model_name DQS))))

By Pin_name

(Package_models

(DQ

(File pkg1.mod)

(Subckt (Corner pkg1_typ pkg1_min pkg1_max))

(Pin_name (List A1 A2 A3 A4 A5 A6 A7 A8))

(Length (Range 15 11 21))

(Parameters Length)

(Dependency_Table

(ParameterNames Pin_name Length)

(ColumnTypes In Out_Match)

(A1 11)

(A2 12)

(A3 14)

(A4 14)

(A5 11)

(A6 21)

(A7 18)

(A8 11)

)

)

Signal / Power Coupling

(Package_models

(DQ

(File pkg1.mod)

(Subckt (Corner pkg1_typ pkg1_min pkg1_max))

(Length (Range 15 11 21))

(Parameters Length)

(Model_ports

(1 (Type Pin) (Channel 1) (Victim True) (Model_name DQ))

(2 (Type Pad)(Channel 1) (Victim True) (Model_name DQ))

(3 (Type Pin) (Channel 2) (Victim False) (Model_name DQ))

(4 (Type Pad)(Channel 2) (Victim False) (Model_name DQ))

(5 (Type Pin) (Channel 3) (Victim False) (Model_name DQ))

(6 (Type Pad)(Channel 3) (Victim False) (Model_name DQ))

(7 (Type Pin) (Channel 4)(Victim False)(Polarity +)(Model_name DQS))

(8 (Type Pin) (Channel 4)(Victim False)(Polarity -)(Model_name DQS))

(9 (Type Pad)(Channel 4)(Victim False)(Polarity +)(Model_name DQS))

(10(Type Pad)(Channel 4)(Victim False)(Polarity -)(Model_name DQS))

(11(Type Pin) (Supply VDD))

(12(Type Pad)(Supply VDD))

)

)

Sparse Ports

```
(Package_models
  (DDR3_DQ1 (Tstonefile package.s1000p)
    (Model_Ports
      (1 (Type Pin) (Pin_name A1)) |DQ1
      (501 (Type Pad) (Pad_name D.A1)) |DQ1
      (102 (Type Pin) (Pin_name B1)) |VDD
      (202 (Type Pin) (Pin_name B2)) |VDD
      (302 (Type Pin) (Pin_name B3)) |VQQ
      (402 (Type Pin) (Pin_name B4)) |VQQ
      (502 (Type Pin) (Pin_name B5)) |VSS
      (602 (Type Pin) (Pin_name B6)) |VSS
      (752 (Type Pad) (Pad_name S7)) |VDD
      (852 (Type Pad) (Pad_name S1)) |VQQ
      (952 (Type Pad) (Pad_name T1)) |VSS
    )
  )
)
```

It is assumed that the EDA tool will extract an s11p from the s1000p

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